



Part Number: XZM2ACY53W 1.6x0.8mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Features

- $\bullet 1.6 mmx 0.8 mm$ SMT LED, 1.1 mm thickness.
- •Low power consumption.
- •Wide viewing angle.
- •Ideal for backlight and indicator.
- •Various colors and lens types available.
- \bullet Package: 2000pcs / reel .
- •Moisture sensitivity level : level 3.
- $\bullet RoHS$ compliant.

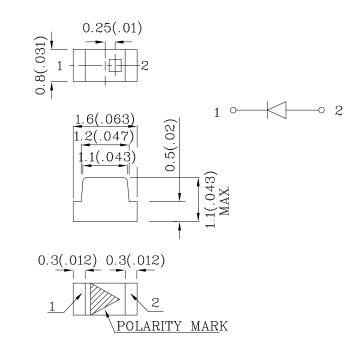




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Rating (TA=25°C)	M2ACY (AlInGaP)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA
Power Dissipation	Рт	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	C



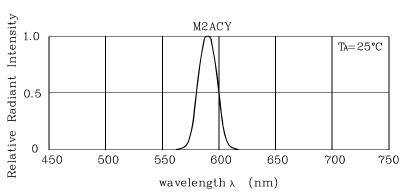
Operating Characteristic (TA=25°C)	M2ACY (AlInGaP)	Unit	
Forward Voltage (Typ.) (IF=20mA)	O COL		
Forward Voltage (Max.) (IF=20mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	590	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	589	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	20	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Inte (IF=:	Luminous Intensity (IF=20mA) mcd		Viewing Angle 2 0 1/2
				min.	typ.		
XZM2ACY53W	Yellow	AlInGaP	Water Clear	110	297	590	120°
Published Date :	JAN 12,2009	Drawing N	o: XDSB2790	V1	Checked : I	3.L.LIU	P.1/4

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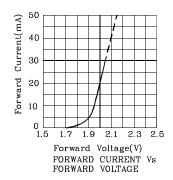
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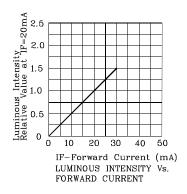


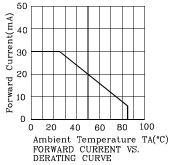


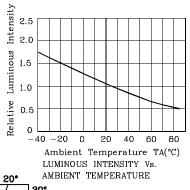
RELATIVE INTENSITY Vs. WAVELENGTH

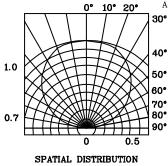
❖ M2ACY











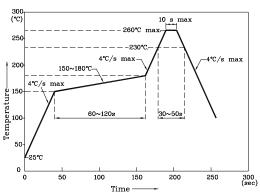
Published Date : JAN 12,2009 Drawing No : XDSB2790 V1 Checked : B.L.LIU P.2/4

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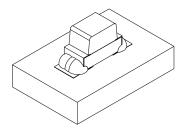
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

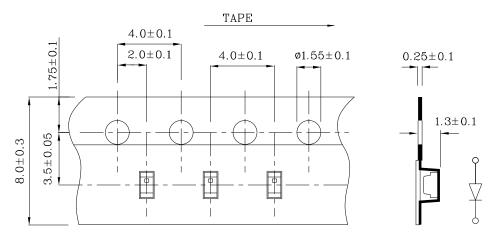
Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:
 - 1. Maximum soldering temperature should not exceed 260°c.
 - 2. Recommended reflow temperature: $145^{\circ}c-260^{\circ}c$.
 - Do not put stress to the epoxy resin during high temperatures conditions.
- **❖** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)
 - 0.8 0.85 0.8
- ❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

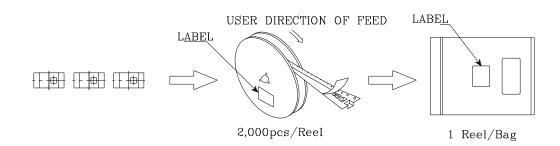


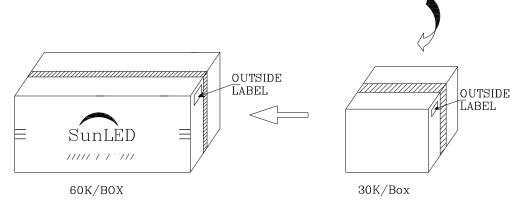
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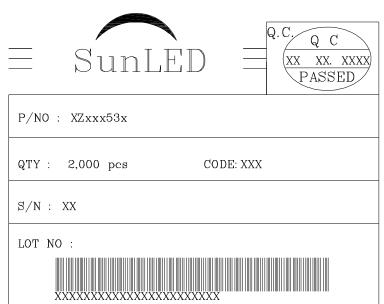
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PACKING & LABEL SPECIFICATIONS

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RoHS Compliant